



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-05
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STH275N8F7-6AG	R2(4*OD8LA52	A	SH1A	2017-09-05
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	10.2 - 9.15 - 4.5	7	Through-hole	
Comment	Package: H2PAK 6 & 7 LEAD			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

Query : California Prop65 list, dated 21st October 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.20	Die	146
Lead	17.76	Soft solder	12867
Antimony trioxide	8.40	Encapsulation	6087

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	RZ(4*OD8LA52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	21.125	mg	supplier	die	Silicon (Si)	7440-21-3		20.267	mg	959385	14686				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.336	mg	15905	243				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.083	mg	3929	60				
				supplier	metallization	Silver (Ag)	7440-22-4		0.049	mg	2320	36				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.037	mg	1751	27				
				supplier	metallization	Tungsten (W)	7440-33-7		0.084	mg	3976	61				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.082	mg	3882	59				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.010	mg	473	7				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.119	mg	5633	86				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.009	mg	426	7				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.049	mg	2320	36				
				Leadframe	Copper & its alloys	620.276	mg	supplier	alloy	Copper (Cu)	7440-50-8		619.470	mg	998701	448891
								supplier	alloy	Iron (Fe)	7439-89-6		0.285	mg	459	207
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.521	mg	840	378				
Soft solder	Solder	18.593	mg	JIG - R	solder	Lead (Pb)	7439-92-1		17.756	mg	954983	12867				
				supplier	solder	Silver (Ag)	7440-22-4		0.465	mg	25009	337				
				supplier	solder	Tin (Sn)	7440-31-5		0.372	mg	20008	270				
Bonding wires	Other Nonferrous metals & alloys	0.233	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.232	mg	995708	168				
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	4292	1				
				supplier	Ribbon	Aluminium (Al)	7429-90-5		17.559	mg	1000000	12724				
Encapsulation	Other Organic Materials	699.776	mg	supplier	mold compound	Silica, vitreous	60676-86-0		575.916	mg	823001	417330				
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		48.984	mg	70000	35496				
				supplier	mold compound	Phenol resin	9003-35-4		27.991	mg	40000	20283				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		20.993	mg	30000	15212				
				supplier	mold compound	Antimony Trioxide	1309-64-4		8.397	mg	12000	6085				
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		13.996	mg	20001	10142				
				supplier	mold compound	Carbon black	1333-86-4		3.499	mg	5000	2536				
connections coating	Solder	2.438	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.438	mg	1000000	1767				